

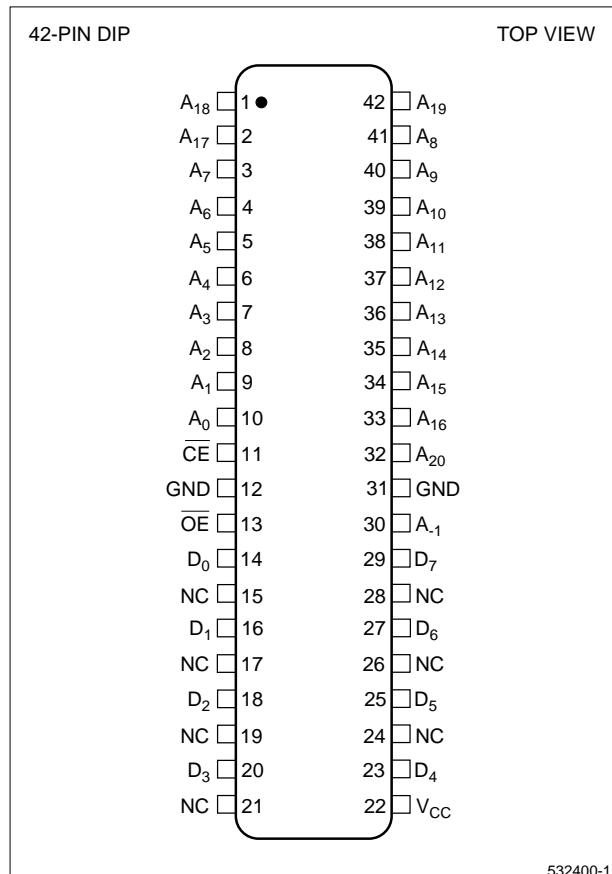
**LH5324000**

## **CMOS 24M (3M × 8) MROM**

## FEATURES

- 3,145,728 × 8 bit organization
  - Access time: 150 ns (MAX.)
  - Supply current:
    - Operating: 65 mA (MAX.)
    - Standby: 100 µA (MAX.)
  - TTL compatible I/O
  - Three-state output
  - Single +5 V Power supply
  - Static operation
  - When the address input at both  $A_{19}$  and  $A_{20}$  is high level, outputs become high impedance irrespective of  $\overline{CE}$  or  $\overline{OE}$ .
  - Package:  
42-pin, 600-mil DIP
  - Others:
    - Non programmable
    - Not designed or rated as radiation hardened
    - CMOS process (P type silicon substrate)

## PIN CONNECTIONS



**Figure 1. Pin Connections**

## DESCRIPTION

The LH5324000 is a 24M-bit CMOS mask-programmable ROM organized as  $3,145,728 \times 8$  bits. It is fabricated using silicon-gate CMOS process technology.

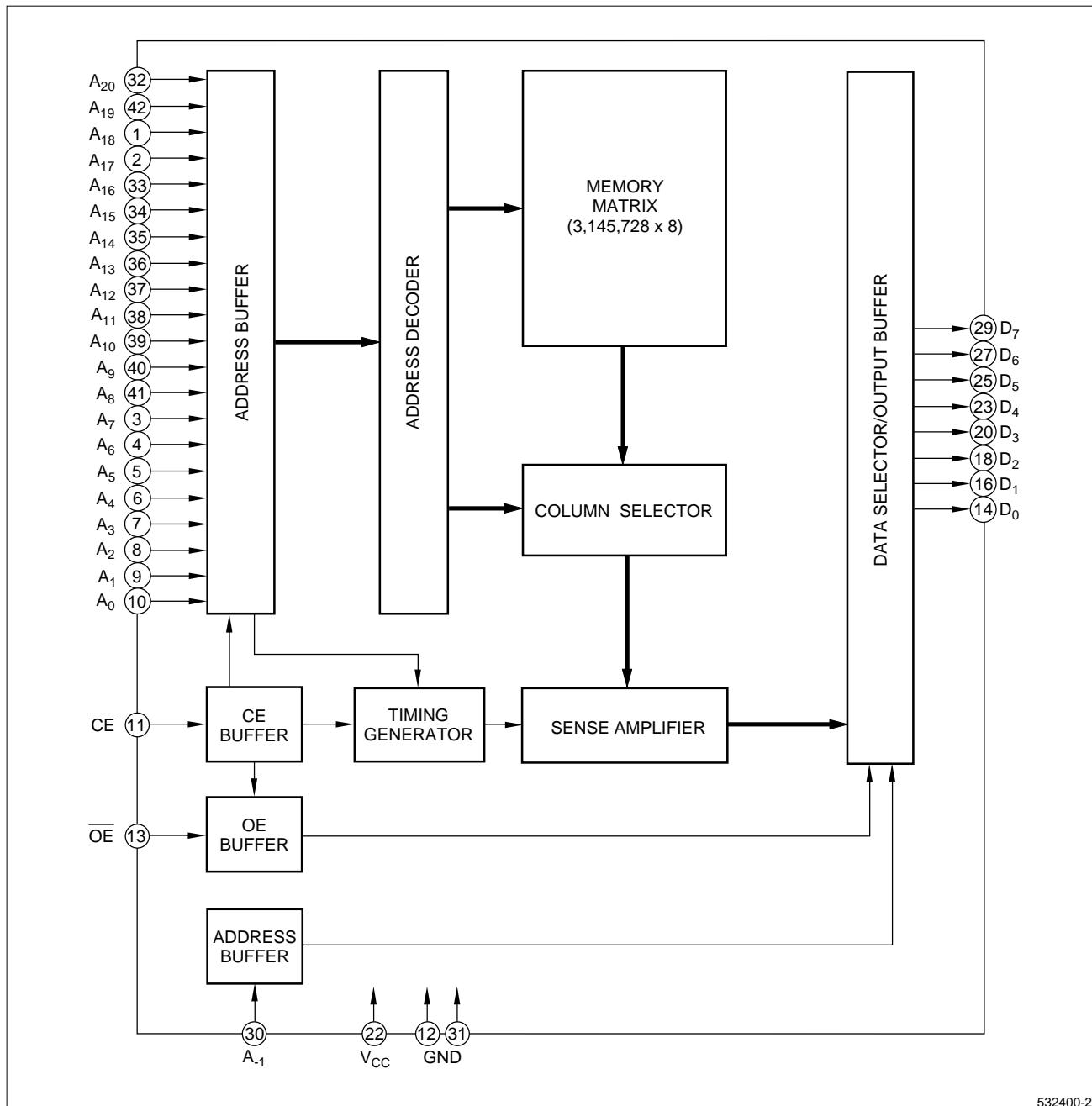


Figure 2. LH5324000 Block Diagram

**PIN DESCRIPTION**

SIGNAL	PIN NAME
$A_1 - A_{20}$	Address input
$D_0 - D_7$	Data output
CE	Chip enable input
OE	Output enable input

SIGNAL	PIN NAME
$V_{CC}$	Power pin (+5 V)
GND	Ground
NC	No connection

**TRUTH TABLE**

<b><math>\overline{CE}</math></b>	<b><math>\overline{OE}</math></b>	<b>A-1 - A<sub>18</sub></b>	<b>A<sub>19</sub></b>	<b>A<sub>20</sub></b>	<b>DATA OUTPUT</b>	<b>SUPPLY CURRENT</b>
					<b>D<sub>0</sub> - D<sub>7</sub></b>	
H	X	X	X	X	High-Z	Standby ( $I_{SB}$ )
L	H	X	X	X	High-Z	Operating ( $I_{CC}$ )
L	L	X	L	L	Output	Operating ( $I_{CC}$ )
L	L	X	L	H	Output	Operating ( $I_{CC}$ )
L	L	X	H	L	Output	Operating ( $I_{CC}$ )
L	L	X	H	H	High-Z	Operating ( $I_{CC}$ )

**NOTES:**

1. X = Don't care; High-Z = High-impedance
2. When the address inputs become HIGH to both A<sub>19</sub> and A<sub>20</sub>, the data does not exist in this address area, the data outputs become "High Impedance".

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	RATING	UNIT
Supply voltage	V <sub>CC</sub>	-0.3 to +7.0	V
Input voltage	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> + 0.3	V
Output voltage	V <sub>OUT</sub>	-0.3 to V <sub>CC</sub> + 0.3	V
Operating temperature	T <sub>OPR</sub>	0 to +70	°C
Storage temperature	T <sub>STG</sub>	-65 to +150	°C

**RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 0 to +70°C)**

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V <sub>CC</sub>	4.5	5.0	5.5	V

**DC ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 5 V ± 10%, T<sub>A</sub> = 0 to +70°C)**

PARAMETER	SYMBOL	CONDITIONS	MIN.	MAX.	UNIT	NOTE
Input 'High' voltage	V <sub>IH</sub>	—	2.2	V <sub>CC</sub> + 0.3	V	—
Input 'Low' voltage	V <sub>IL</sub>	—	-0.3	0.8	V	—
Output 'High' voltage	V <sub>OH</sub>	I <sub>OH</sub> = -400 μA	2.4	—	V	—
Output 'Low' voltage	V <sub>OL</sub>	I <sub>OL</sub> = 2.0 mA	—	0.4	V	—
Input leakage current	I <sub>LI</sub>	V <sub>IN</sub> = 0 V to V <sub>CC</sub>	—	10	μA	—
Output leakage current	I <sub>LO</sub>	V <sub>OUT</sub> = 0 V to V <sub>CC</sub>	—	10	μA	1
Operating current	I <sub>CC1</sub>	t <sub>RC</sub> = 150 ns	—	65	mA	2
	I <sub>CC2</sub>	t <sub>RC</sub> = 1 μs	—	55	mA	
Standby current	I <sub>SB1</sub>	CE = V <sub>IH</sub>	—	2	mA	—
	I <sub>SB2</sub>	CE = V <sub>CC</sub> - 0.2 V	—	100	μA	
Input capacitance	C <sub>IN</sub>	f = 1 MHz, t <sub>A</sub> = 25°C	—	10	pF	—
Output capacitance	C <sub>OUT</sub>		—	10	pF	—

**NOTES:**

1. CE = V<sub>IH</sub>, OE = V<sub>IH</sub>
2. V<sub>IN</sub> = V<sub>IH</sub> or V<sub>IL</sub>, CE = V<sub>IL</sub>, output is open

**AC ELECTRICAL CHARACTERISTICS ( $V_{CC} = +5 \text{ V} \pm 10\%$ ,  $T_A = 0 \text{ to } +70^\circ\text{C}$ )**

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Read cycle time	$t_{RC}$	150	—	ns	—
Address access time	$t_{AA}$	—	150	ns	—
Chip enable access time	$t_{ACE}$	—	150	ns	—
Output enable delay time	$t_{OE}$	—	70	ns	—
Output hold time	$t_{OH}$	5	—	ns	—
Output floating time	$t_{CHZ}$	—	60	ns	1
	$t_{OHZ}$	—	60	ns	
	$t_{AHZ}$	—	70	ns	

**NOTE:**

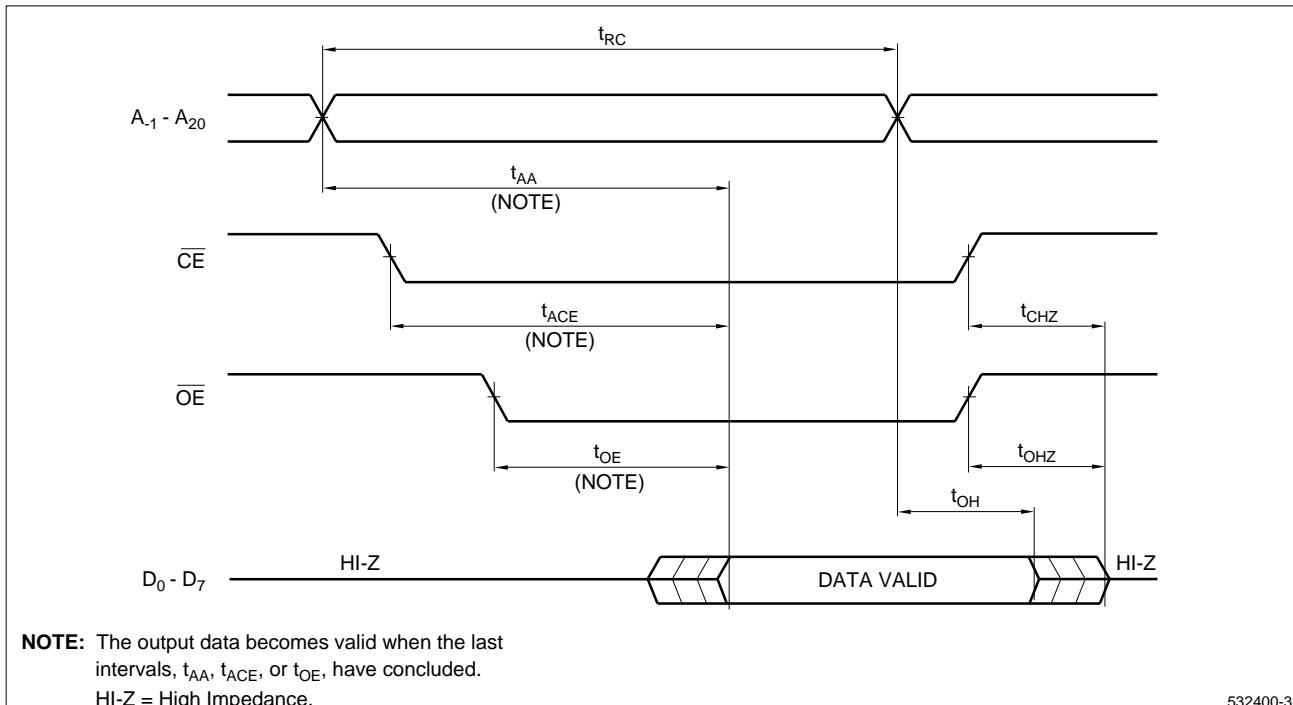
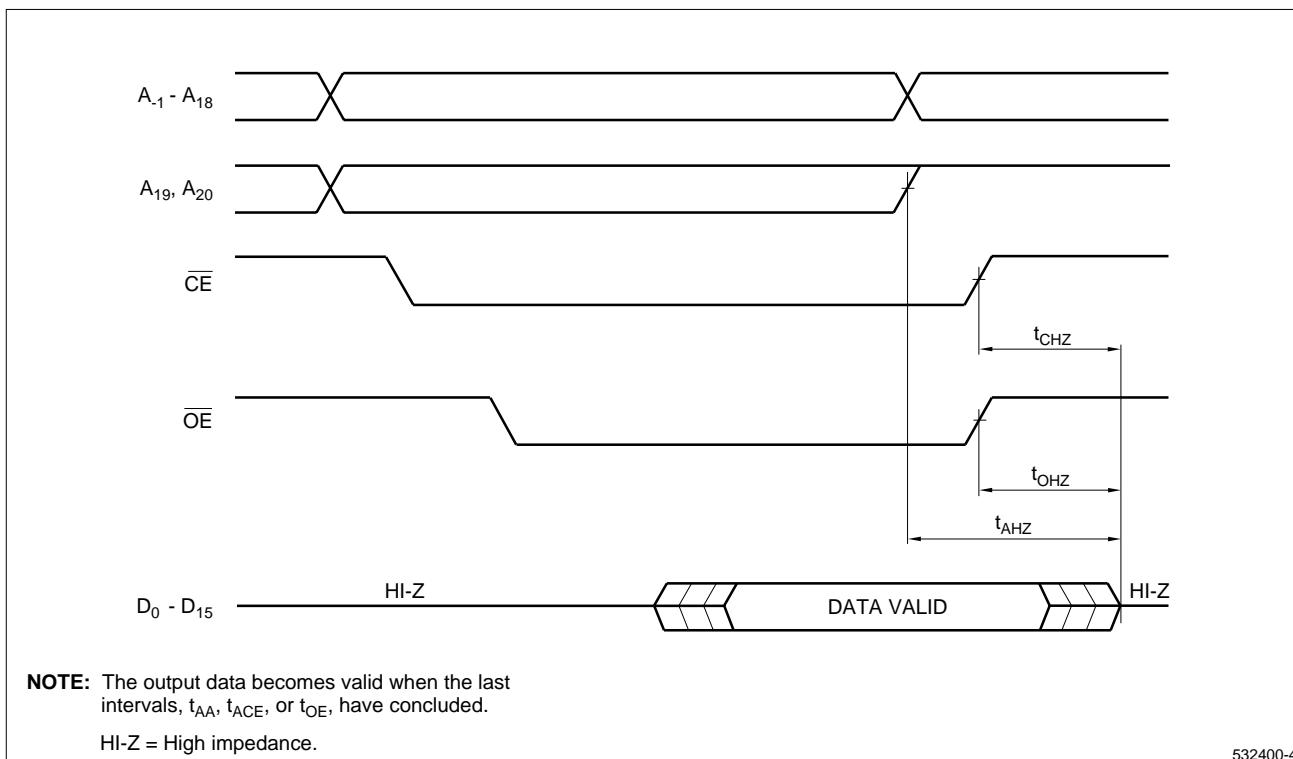
1. Determined by the time for the output to be opened. (Irrespective of output voltage)

**AC TEST CONDITIONS**

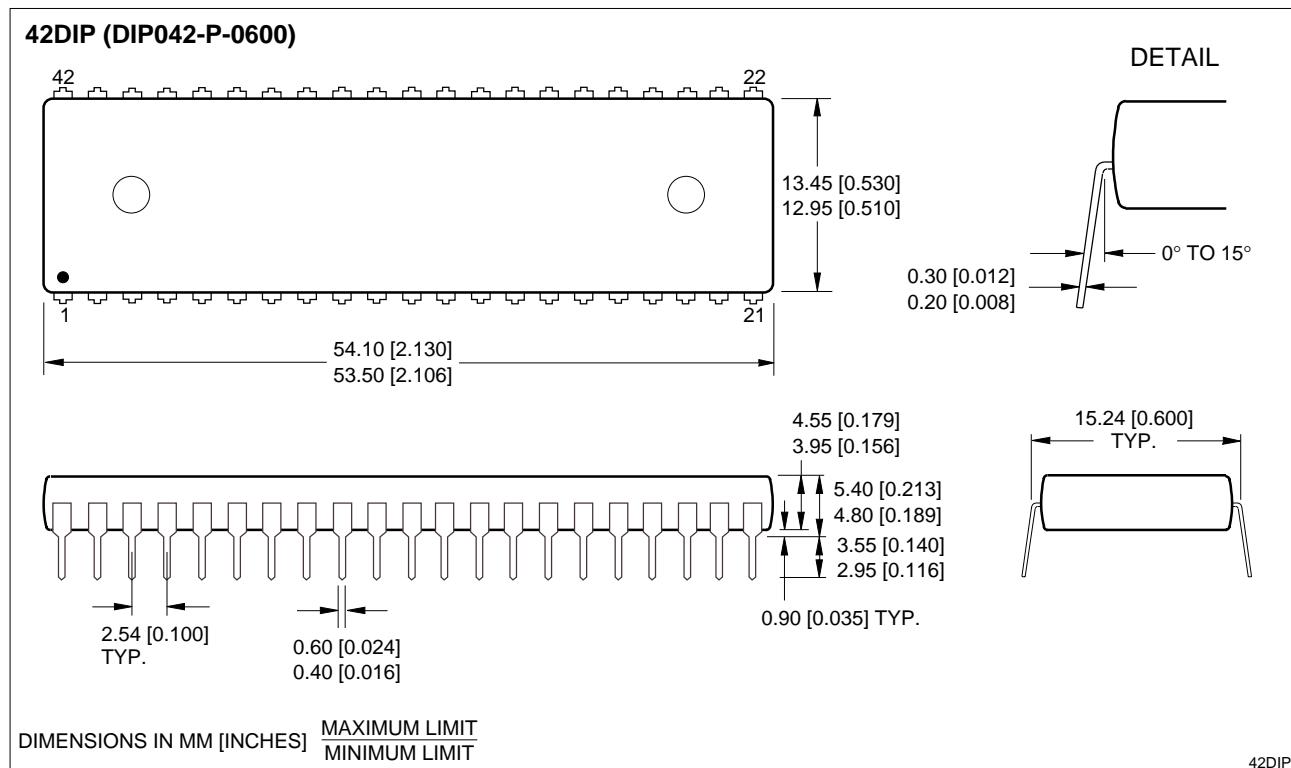
PARAMETER	RATING
Input voltage amplitude	0.6 V to 2.4 V
Input signal rise time	10 ns
Input signal fall time	10 ns
Input reference level	1.5 V
Output reference level	0.8 V, 2.2 V
Output load condition	1TTL + 100 pF

**NOTE:**

It is recommended that a decoupling capacitor be connected between  $V_{CC}$  and GND-Pin.

**Figure 3. Byte Mode****Figure 4. Word Mode**

## PACKAGE DIAGRAM



## ORDERING INFORMATION

LH532400  
Device Type

D  
Package

42-pin, 600-mil DIP (DIP42-P-600)

CMOS 24M (3M x 8) Mask-Programmable ROM

**Example:** LH532400D (CMOS (24M 3M x 8) Mask-Programmable ROM, 42-pin, 600-mil DIP)

532400-5